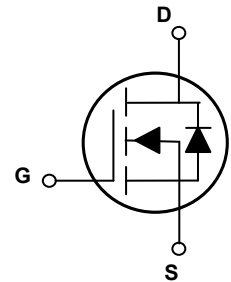
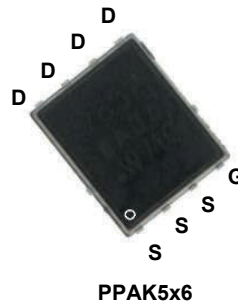


## Main Product Characteristics

$V_{(BR)DSS}$	40V
$R_{DS(ON)}$	6.5m $\Omega$ (Max)
$I_D$	65A



Schematic Diagram

## Features and Benefits

- Advanced MOSFET process technology
- Ideal for high efficiency switched mode power supplies
- Low on-resistance with low gate charge
- Fast switching and reverse body recovery



## Description

The GSGP6R504 utilizes the latest techniques to achieve high cell density and low on-resistance. These features make this device extremely efficient and reliable for use in high efficiency switch mode power supplies and a wide variety of other applications.

## Absolute Maximum Ratings ( $T_A=25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Max.	Unit
Drain-Source Voltage	$V_{DS}$	40	V
Gate-to-Source Voltage	$V_{GS}$	$\pm 20$	V
Continuous Drain Current, @ Steady-State ( $T_C=25^\circ\text{C}$ )	$I_D$	65	A
Continuous Drain Current, @ Steady-State ( $T_C=100^\circ\text{C}$ )		43	A
Pulsed Drain Current ( $T_C=25^\circ\text{C}$ ) <sup>1</sup>	$I_{DM}$	260	A
Power Dissipation ( $T_C=25^\circ\text{C}$ ) <sup>2</sup>	$P_D$	47	W
Single Pulse Avalanche Energy <sup>5</sup>	$E_{AS}$	33.6	mJ
Single Pulse Current	$I_{AS}$	11.6	A
Thermal Resistance Junction-to-Ambient (PCB Mounted, Steady-State)	$R_{\theta JA}$	40	$^\circ\text{C/W}$
Thermal Resistance Junction-to-Case	$R_{\theta JC}$	2.66	$^\circ\text{C/W}$
Operating Junction and Storage Temperature Range	$T_J/T_{STG}$	-55 to +150	$^\circ\text{C}$
Soldering Temperature (SMD)	$T_{sold}$	260	$^\circ\text{C}$

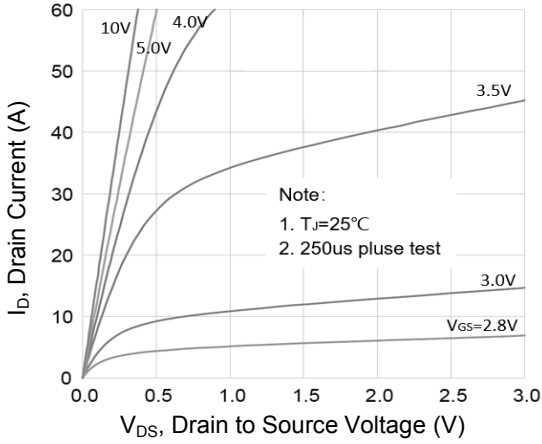
**Electrical Characteristics** ( $T_A=25^\circ\text{C}$  unless otherwise specified)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
<b>On / Off Characteristics</b>						
Drain-to-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS}=0V, I_D=250\mu A$	40	-	-	V
Drain-to-Source Leakage Current	$I_{DSS}$	$V_{DS}=40V, V_{GS}=0V, T_J=25^\circ\text{C}$	-	-	1.0	$\mu A$
		$V_{DS}=40V, V_{GS}=0V, T_J=125^\circ\text{C}$	-	2.0	-	
Gate-to-Source Forward Leakage	$I_{GSS}$	$V_{DS}=0V, V_{GS}=\pm 20V$	-	-	$\pm 100$	nA
Static Drain-to-Source On-Resistance	$R_{DS(ON)}$	$V_{GS}=10V, I_D=20A$	-	5.1	6.5	m $\Omega$
		$V_{GS}=4.5V, I_D=20A$	-	7.3	9.5	
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=250\mu A$	1.1	-	2.8	V
<b>Dynamic and Switching Characteristics</b>						
Input Capacitance	$C_{iss}$	$V_{GS}=0V, V_{DS}=15V, f=1\text{MHz}$	-	860	-	$\mu F$
Output Capacitance	$C_{oss}$		-	495	-	
Reverse Transfer Capacitance	$C_{rss}$		-	36	-	
Total Gate Charge <sup>3,4</sup>	$Q_g$	$I_D=9A, V_{DD}=15V, V_{GS}=10V$	-	15.5	-	nC
Gate-to-Source Charge <sup>3,4</sup>	$Q_{gs}$		-	3.2	-	
Gate-to-Drain ("Miller") Charge <sup>3,4</sup>	$Q_{gd}$		-	2.2	-	
Gate-to-Plateau <sup>3,4</sup>	$V_{plateau}$		-	3.3	-	V
Turn-on Delay Time <sup>3,4</sup>	$t_{d(on)}$	$V_{DD}=20V, V_{GS}=10V, R_G=3\Omega, I_D=9A$	-	4.4	-	nS
Rise Time <sup>3,4</sup>	$t_r$		-	31	-	
Turn-Off Delay Time <sup>3,4</sup>	$t_{d(off)}$		-	21	-	
Fall Time <sup>3,4</sup>	$t_f$		-	12	-	
Gate Resistance	$R_g$	$f=1\text{MHz}$	-	2.2	-	$\Omega$
<b>Drain-Source Ratings and Characteristics</b>						
Continuous Source Current (Body Diode)	$I_S$	MOSFET symbol showing the integral reverse p-n junction diode.	-	-	65	A
Diode Pulse Current	$I_{S,pulse}$		-	-	260	A
Diode Forward Voltage	$V_{SD}$	$I_S=5A, V_{GS}=0V$	-	-	1.4	V
Reverse Recovery Time <sup>3</sup>	$T_{rr}$	$I_S=2A, V_{GS}=0V, V_R=30V, dI_F/dt=100A/\mu s$	-	29	-	nS
Reverse Recovery Charge <sup>3</sup>	$Q_{rr}$		-	14	-	nC

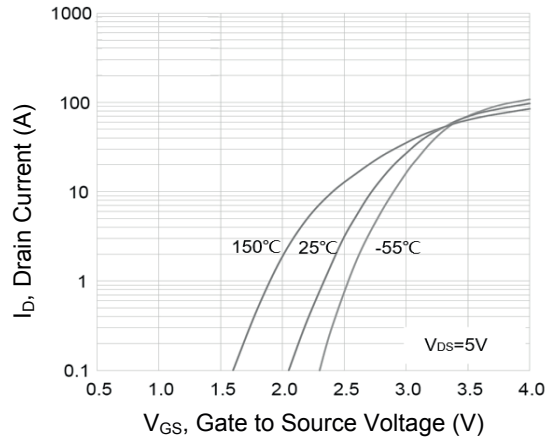
Notes:

1. Pulse time of 5 $\mu s$ .
2. The dissipated power value will change with the temperature. When it is greater than 25 $^\circ\text{C}$ , the dissipated power value will decrease by 0.55 $^\circ\text{C}/\text{W}$  for every 1 degree of temperature increase.
3. Pulse test: Pulse width  $\leq 300\mu s$ , duty cycle  $\leq 2\%$ .
4. Basically unaffected by operating temperature.
5.  $L=0.5\text{mH}, R_G=25\Omega, V_{DD}=24V, T_J=25^\circ\text{C}$ .

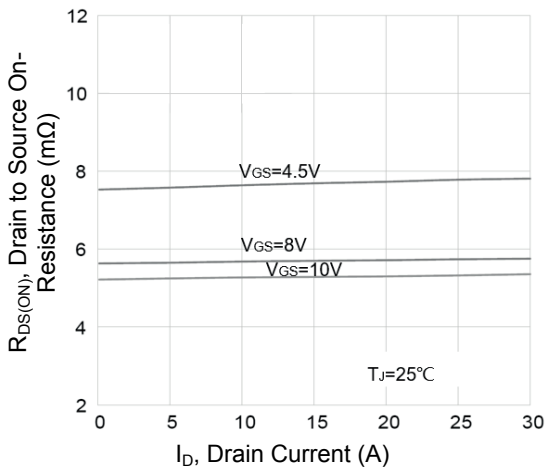
**Typical Electrical and Thermal Characteristic Curves**



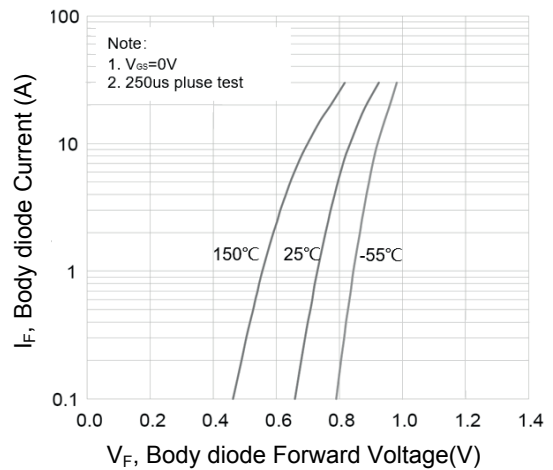
**Figure 1. Typical Output Characteristics**



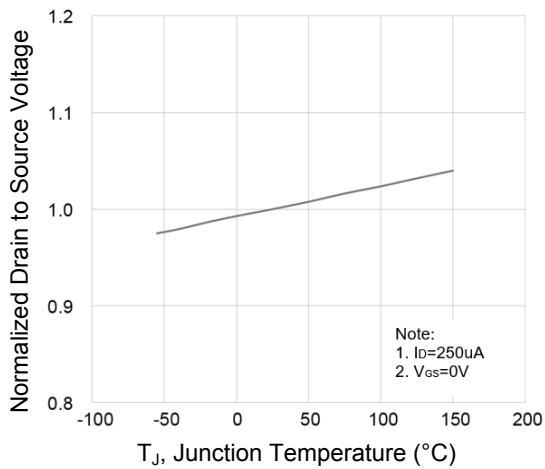
**Figure 2. Transfer Characteristics**



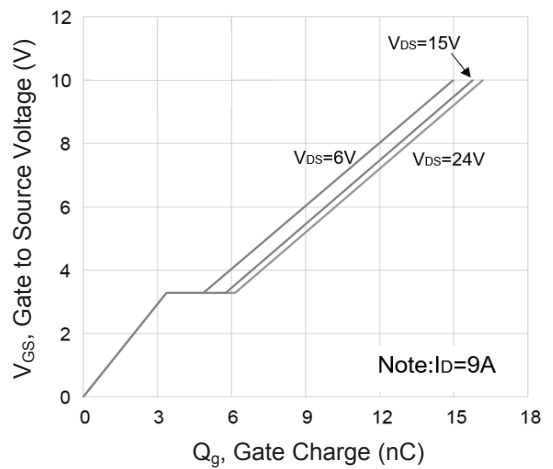
**Figure 3.  $R_{DS(ON)}$  vs. Drain Current**



**Figure 4. Body Diode Characteristics**

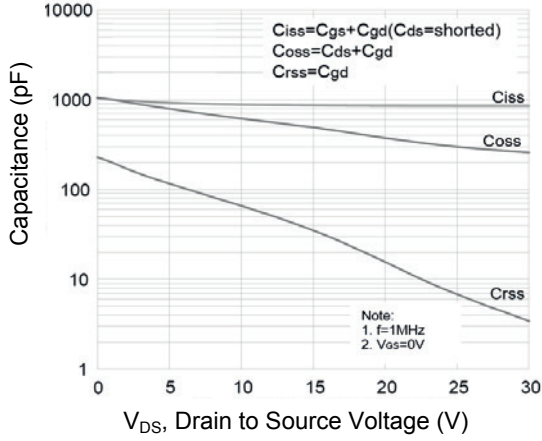


**Figure 5. Normalized  $BV_{DS}$  vs.  $T_J$**

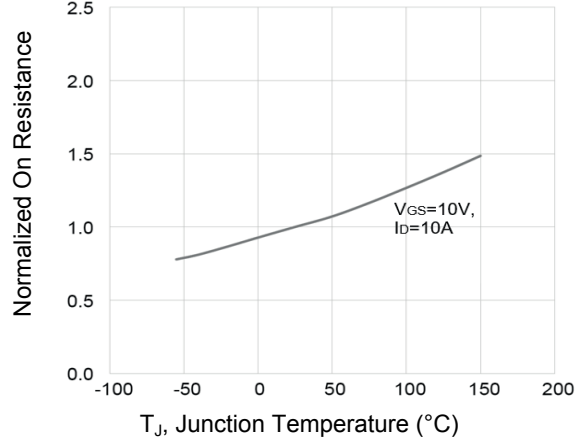


**Figure 6. Gate Charge**

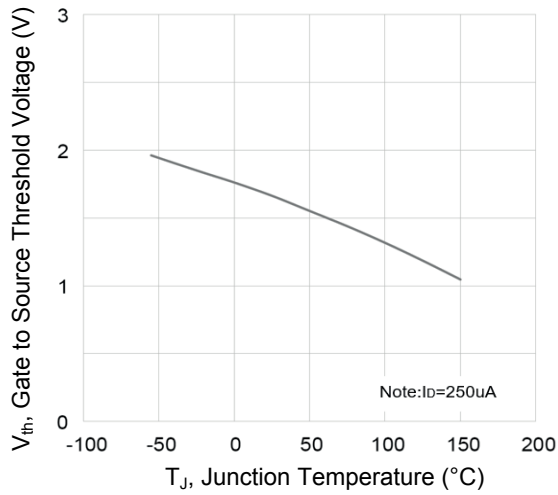
**Typical Electrical and Thermal Characteristic Curves**



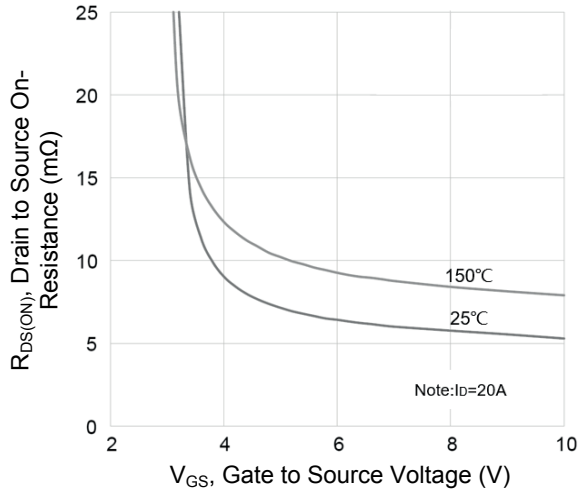
**Figure 7. Capacitance Characteristics**



**Figure 8. Normalized  $R_{DS(ON)}$  vs.  $T_J$**

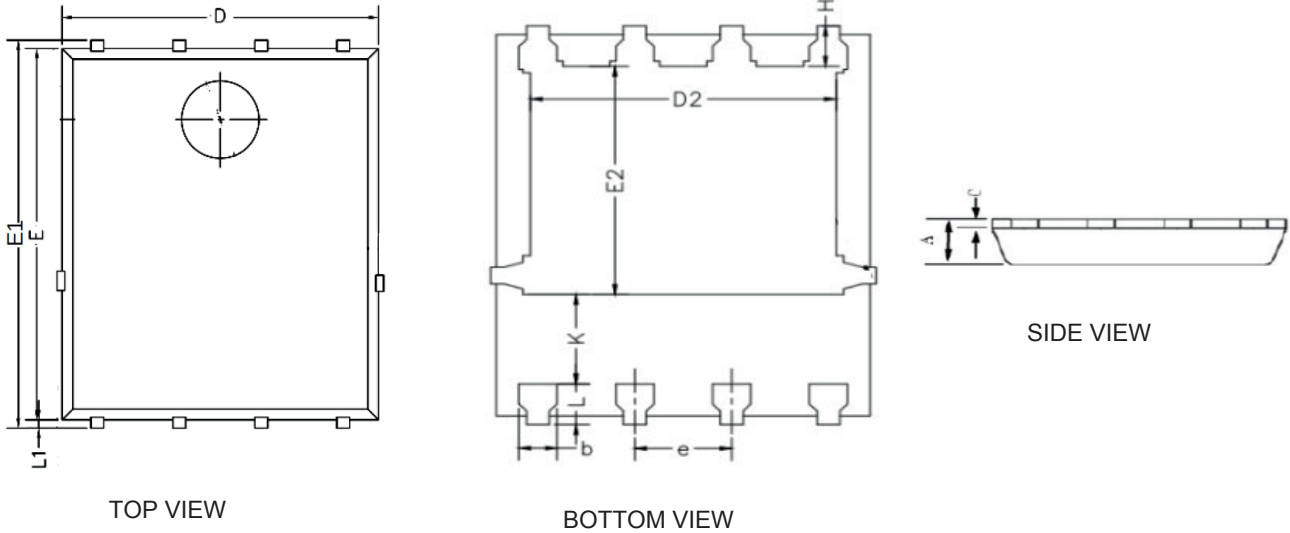


**Figure 9.  $V_{th}$  vs.  $T_J$**



**Figure 10.  $R_{DS(ON)}$  vs.  $V_{GS}$**

**Package Outline Dimensions (PPAK5x6)**



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.90	1.20	0.035	0.047
b	0.30	0.55	0.012	0.022
C	0.15	0.35	0.006	0.014
D	4.70	5.20	0.185	0.205
D2	3.76	4.20	0.148	0.165
E2	3.30	3.85	0.130	0.152
E	5.60	5.90	0.220	0.232
E1	5.80	6.20	0.228	0.244
K	1.10	-	0.043	-
H	0.45	0.75	0.018	0.030
L	0.45	0.75	0.018	0.030
L1	0.25	0.45	0.010	0.018
e	1.27 BSC		0.050 BSC	

**Order Information**

Device	Package	Marking	Carrier	Quantity
GSGP6R504	PPAK5x6	P6R504	Tape & Reel	5,000 Pcs / Reel

For more information, please contact us at: [inquiry@goodarksemi.com](mailto:inquiry@goodarksemi.com)